

Full Material Declaration

物質宣告表

Customer name							
Manufacure name	Innolux Corporation			Issue Date (yyyy/mm/dd)	2024/1/30		
Model name	G104XCE-L01			Product weight (g)	320		
Contact person	Chen Meifang			E-mail address	meifang.chen@innolux.com		
Part Name	Part mass (g)	Homogeneous Material name	Material mass (g)	Substance name	CAS No.	weigh% of substance	Remark
Glass	71.428	Glass	71.428	Fiber Glass Wool	65997-17-3	100	Glass, oxide, chemicals
PF CF	5.76	POLARIZER	5.76	Poly(ethylene terephthalate);PET	25038-59-9	46.296	
				triacetate cellulose film bas	9012-09-3	35.087	
				Poly(vinyl alcohol); PVA	9002-89-5	5.317	
				Boric acid; Orthoboric acid; Boron trihydroxide	10043-35-3 / 11113-50-1	5	成分含量比取系列別最大檢出值換算
				Acrylates copolymer;	25133-97-5	8.3	
		INK	0.00001	2-Butanone;Ethyl methyl ketone	78-93-3	85	
				Others	-	8	導電劑/油墨廠商因商業機密，不願意揭露CAS No.
				Others	-	7	樹脂/油墨廠商因商業機密，不願意揭露CAS No.
PF TFT	5.48	POLARIZER	5.48	Poly(ethylene terephthalate);PET	25038-59-9	46.296	
				triacetate cellulose film bas	9012-09-3	35.087	
				Poly(vinyl alcohol); PVA	9002-89-5	5.317	
				Boric acid; Orthoboric acid; Boron trihydroxide	10043-35-3 / 11113-50-1	5	架橋劑
				Acrylates copolymer;	25133-97-5	8.3	
		INK	0.00001	2-Butanone;Ethyl methyl ketone	78-93-3	15	
				Ethanol	64-17-5	35	
				Polyacrylic acid; 2-Propenoic acid homopolymer	9003-01-4	35	

				1-Methoxy-2-propyl acetate	108-65-6	7.5	
				Iron oxide;Iron oxide red	1332-37-2	7.5	藍色色粉 (群青藍)
LN	9.58	LN	9.6	Poly(ethylene terephthalate);PET	25038-59-9	90	
				9,9-Bis[4-(2-acryloyloxyethoxy)phenyl]fluorene;	161182-73-6	10	
LH	9.65	LH.	9.65	Poly(ethylene terephthalate);PET	25038-59-9	90	
				EBECRYL 600;	71281-65-7	10	
DD	5.40	Diffusion Film	5.4	Poly(ethylene terephthalate);PET	25038-59-9	92.9673	
				Antimony trioxide; Diantimony trioxide; Antimony(III)	1309-64-4	0.0327	
				acrylic resin SS-22	25035-69-2	7	
RN	7.8	Reflector Sheet	7.8	Poly(ethylene terephthalate);PET	25038-59-9	53	
				Titanium dioxide	13463-67-7	16	
				Others	-	23	Polyester resin
				Others	-	8	Polyolefin resin
LGP-I	58.9	LGP	58.9	methyl 2-methylprop-2-enoate; 2-methylprop-2-enoate	9011-87-4	99.1	GH-S是GH-1000S的簡寫
				Methyl methacrylate;	80-62-6	0.9	
IC G-COG	0.01	Au Bump	0.0004	Gold	7440-57-5	98.16	
				Tungsten;	7440-33-7	1.75	
				Titanium	7440-32-6	0.09	
		Wafer	0.0086	Silicon;	7440-21-3	99.6419	
				Arsenic	7440-38-2	0.0001	
				Boron;	7440-42-8	0.003	
				Phosphorus	7723-14-0	0.003	
				Aluminium;	7429-90-5	0.15	
				Titanium	7440-32-6	0.1	
				Copper (metallic)	7440-50-8	0.002	
				Tungsten;	7440-33-7	0.1	
IC S-COF	0.12	Au Bump	0.0001	Gold	7440-57-5	98.16	
				Tungsten;	7440-33-7	1.75	
				Titanium	7440-32-6	0.09	
		Base film	0.0562	Silicon dioxide	7631-86-9	1	
				Others	-	99	Inert Polyimide film
		Copper	0.0391	Copper (metallic)	7440-50-8	100	
		Resin	0.0035	N,N-DIGLYCIDYL-4-GLYCIDYLOXYANILINE;4-(2-Oxiranylmethoxy)-N,N-bis(2-oxiranylmethyl)aniline	5026-74-4	20	
				Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	15	

				Solvent black 7;C.I. 50415:1	8005-02-5	1	
				Others	-	60	Acid anhydride type hardener 酸酐型固化剂,非INX文件管 控酸酐類物質
				Others	-	4	Additives(trade secret)
		SR	0.0101	Others	-	80	Polyimide resin modified
				4,4'-Methylenebis(N,N-diglycidylaniline);4,4'- Methylenebis[N,N-bis(2,3-epoxypropyl)aniline]	28768-32-3	9	
				Others	-	1	Pigment(trade secret)
				Others	-	10	Layered double hydroxide
		Sn Plating	0.0017	Others	-	30	Alkylsulfonic acid
				Others	-	15	Tin(II) Alkylsulfonate
				Others	-	39.5	water
				Thiourea;Thiocarbamide	62-56-6	15	
				Phenol	108-95-2	0.5	
		Wafer	0.0105	Silicon;	7440-21-3	99.7084	
				Arsenic	7440-38-2	0.0002	
				Boron;	7440-42-8	0.0001	
				Phosphorus	7723-14-0	0.0001	
				Aluminium;	7429-90-5	0.2	
				Titanium	7440-32-6	0.055	
				Copper (metallic)	7440-50-8	0.001	
				Tungsten;	7440-33-7	0.035	
				Antimony	7440-36-0	0.0002	
IC Tcon	0.18	COPPER WIRE	0.0005	Copper (metallic)	7440-50-8	96.55	
				Palladium;E 101O/W	7440-05-3	3.1	
				Gold	7440-57-5	0.35	
		DIE	0.0015	Silicon;	7440-21-3	99.05233	
				Boron;	7440-42-8	0.00004	
				Phosphorus	7723-14-0	0.00015	
				Arsenic	7440-38-2	0.0003	
				Germanium;Germaniumelement	7440-56-4	0.02109	
				Fluorine	7782-41-4	0.0002	
				Aluminium;	7429-90-5	0.20663	
				Copper (metallic)	7440-50-8	0.59635	
				Nickel	7440-02-0	0.00471	
				Titanium	7440-32-6	0.00125	

				Tantalum;tantalum, metal	7440-25-7	0.10892	
				Tungsten;	7440-33-7	0.008	
		DIE ATTACH PASTE	0.0003	Silver;	7440-22-4	73.5	
				Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	4	
				Others	-	6	Epoxy resin
				1,4-Bis((2,3-epoxypropoxy)methyl)cyclohexane;Cyclohexane,1,4-bis[(2,3-epoxypropoxy)methyl]- (8CI)	14228-73-0	4	
				Ethylene dimethacrylate;1,2-Ethandiol dimethacrylate	97-90-5	6	
				Others	-	5	Hardener
				Dicyanodiamide;1-Cyanoguanidine	461-58-5	0.5	
				1,1-Di(tert-butylperoxy)cyclohexane;Cyclohexylidenebis(tert-butyl)peroxide	3006-86-8	1	
		Epoxy molding compound	0.0964	Others	-	3	Epoxy Resin A(Trade Secret)
				Others	-	3	Epoxy Resin A(Trade Secret)
				Silicon dioxide;Silica	60676-86-0	78.45	
				Carbon Black	1333-86-4	0.55	
				Silicon dioxide	7631-86-9	7.5	
				Others	-	7.5	Phenol Resin(Trade Secret)
		Gold Wire	0.0002	Gold	7440-57-5	99.0475	
				Palladium;E 101O/W	7440-05-3	0.95	
				Calcium;	7440-70-2	0.002	
				Beryllium	7440-41-7	0.0005	
		LEAD FRAME-MATERIAL	0.003	Silver;	7440-22-4	100	
		Lead Frame	0.0695	Copper (metallic)	7440-50-8	91.9	
				Silicon;	7440-21-3	3.088	
				Magnesium	7439-95-4	0.354	
				Silver;	7440-22-4	3.5	
				Nickel	7440-02-0	1.158	
		Plating	0.005	Tin	7440-31-5	100	
PWM	0.04	Bonding Wire	0.0001	Copper (metallic)	7440-50-8	98.57	
				Palladium;E 101O/W	7440-05-3	1.43	
		Lead Frame	0.0200	Copper (metallic)	7440-50-8	96.46	

				Iron;	7439-89-6	2.28	
				Phosphorus	7723-14-0	0.03	
				Zinc	7440-66-6	0.15	
				Silver;	7440-22-4	1.08	
		Mold Compound	0.0175	Silicon dioxide;Silica	60676-86-0	82	
				Silicon dioxide	7631-86-9	15	
				Carbon Black	1333-86-4	0.2	
				Others	-	0.6	Trade Secret (Catalyst)
				Others	-	0.6	Trade Secret (Epoxy Resin 1)
				Others	-	0.6	Trade Secret (Epoxy Resin 2)
				Others	-	1	Trade Secret (Hardener)
		Silver Paste	0.0001	Silver;	7440-22-4	80	
				Others	-	7	Acrylic resin
				Others	-	4	Polybutadiene derivative
				Others	-	1	Butadiene copolymer
				Others	-	2	Epoxy resin
				Others	-	4	Acrylate
				Others	-	0.5	Trade Secret-Peroxide
				Others	-	1.5	Trade Secret-Additive
		Solder Plating	0.0021	Tin	7440-31-5	100	
		Wafer	0.0021	Silicon;	7440-21-3	99.4	
				Aluminium;	7429-90-5	0.6	
IC	0.05	Die	0.0020	Silicon;	7440-21-3	99.726	
				Aluminium;	7429-90-5	0.163	
				Tungsten;	7440-33-7	0.11	
				Copper (metallic)	7440-50-8	0.001	
		Die attach	0.00024	Silicon dioxide;Silica	60676-86-0	49	
				Others	-	31	Bismaleimide monomer
				Others	-	8	Acrylate monomer
				Others	-	9	Epoxy resin
				Others	-	3	Acrylic resin
		External Plating	0.0006	Tin	7440-31-5	100	
		Lead frame HDS	0.0248	Iron;	7439-89-6	2.1	
				Phosphorus	7723-14-0	0.1	
				Zinc	7440-66-6	0.1	
				Copper (metallic)	7440-50-8	94	
				Silver;	7440-22-4	3.699	
				Lead;	7439-92-1	0.001	Impurity

		Mold compound	0.0174	Others	-	9	Epoxy resin
				Others	-	4	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'-diyl)-bis(oxymethylene))-bis-oxirane
				Others	-	3	Hardener 1(Trade Secret)
				Others	-	3	Hardener 2(Trade Secret)
				Carbon Black	1333-86-4	0.2	
				Silicon dioxide;Silica	60676-86-0	79.899	
				Silicon dioxide	7631-86-9	0.8	
				Others	-	0.001	PAHs (impurity contain in
				Others	-	0.1	Siloxane compound which is
		Wire	0.0001	Copper (metallic)	7440-50-8	97.3	
				Palladium;E 101O/W	7440-05-3	2.7	
MOS	0.01	Bonding wire	0.00002	Gold	7440-57-5	100	
		Die	0.0001	Silicon;	7440-21-3	98.58	
				Nickel	7440-02-0	0.79	
				Silver;	7440-22-4	0.47	
				Gold	7440-57-5	0.16	
		External plating	0.0003	Tin	7440-31-5	98	
				Copper (metallic)	7440-50-8	2	
		LeadFrame-Base material	0.0019	Iron;	7439-89-6	58	
				Nickel	7440-02-0	42	
		Leadframe-surface treatment	0.0003	Copper (metallic)	7440-50-8	100	
		Mold compound	0.0031	Silicon dioxide;Silica	60676-86-0	58.97	
				Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	14.37	
				Phenolic Resin	9003-35-4	7.69	
				Aluminium hydroxide	21645-51-2	17.95	
				Others	-	0.51	Organic phosphorus compounds
				Carbon Black	1333-86-4	0.51	
Diode	0.02	Jump(Clip)	0.0021	Copper (metallic)	7440-50-8	97.6	
				Iron;	7439-89-6	2.4	
		Lead Frame	0.0088	Iron;	7439-89-6	0.15	
				Copper (metallic)	7440-50-8	99.85	
		Lead Free Plating	0.0001	Tin	7440-31-5	99.991	
				Lead;	7439-92-1	0.009	
		dice(Schottky)	0.0011	Silicon;	7440-21-3	99.206	
				Gold	7440-57-5	0.55	

				Arsenic	7440-38-2	0.09	
				Nickel	7440-02-0	0.154	
		high temp solder paste	0.0016	Lead;	7439-92-1	92.5	
				Tin	7440-31-5	5	
				Silver;	7440-22-4	2.5	
		molding compound	0.0051	Silicon dioxide;Silica	60676-86-0	79.7	
				Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	10	
				Phenolic Resin	9003-35-4	10	
				Carbon Black	1333-86-4	0.3	
PCB OE	16.71	Chemical Gold potion	0.0124	Ammonium hydroxide	1336-21-6	2.1	
				Water;dihydrogen oxide	7732-18-5	74.9	
				Others	-	18.5	羧酸
				Others	-	4.5	氨基酸
		Chemical Nickel potion	0.48	Nickel(II) sulfate hexahydrate (1:1:6)	10101-97-0	45	
				Water;dihydrogen oxide	7732-18-5	55	
		Base	6.95	Copper (metallic)	7440-50-8	80.62	
				Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	12.54	
				Fiber Glass Wool	65997-17-3	6.84	
		Marking ink692W	0.0235	Others	-	51	丙烯酸環氧樹脂
				Titanium dioxide	13463-67-7	15	
				Talc	14807-96-6	16	
				Silicon dioxide	7631-86-9	2	
				Poly(ethylene glycol) diacrylate;Glycols,polyethylene, diacrylate (8CI)	26570-48-9	16	
		Phosphor copper sphere	4.19	Copper (metallic)	7440-50-8	99.9	
				Phosphorus	7723-14-0	0.1	
		Copper	2.54	Copper (metallic)	7440-50-8	100	
		Solder mask	0.35	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	10	
				Solvent naphtha	64742-94-5	10	
				Silica, Crystalline	14808-60-7	3	
				(29H,31H-phthalocyaninato(2-)-N29,N30,N31,N32)copper	147-14-8	0.5	
				Pigment Yellow 180;2,2'-[Ethylenebis(oxyphenyl)-2,1-eneazo]]bis[N-(2,3-dihydro-2-oxo-1H-benzimidazol-5-yl)-3-oxo-butanamide	77804-81-0	0.5	

				Barium sulfate;BaSO4	7727-43-7	33	
				2-Methyl-4'-(methylthio)-2-morpholinopropiophenone;2-Methyl-1-[4-(methylthio)phenyl]-2-(4-morpholinyl)-1-propanone	71868-10-5	4.5	
				Dimethicone; Polydimethylsiloxane trimethylsiloxy-terminated	9006-65-9	3	
				Others	-	35	树脂/71281-65-7
				Others	-	0.5	光引发剂/84434-11-7
		PP	2.164	Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	32	
				Fiber Glass Wool	65997-17-3	63	
				Others	-	5	商业机密
Res-SMD	0.0019	Ceramic Substrate 2019	0.002	Aluminum oxide;	1344-28-1	96	
				Silica, Crystalline	14808-60-7	3	
				Magnesium oxide	1309-48-4	1	
		Ni Plating	0.000087	Nickel	7440-02-0	100	
		Sn Plating	0.000078	Tin	7440-31-5	100	
		Conductor Layer 2018	0.000045	Silver;	7440-22-4	64	
				Fiber Glass Wool	65997-17-3	15	
				Terpineol;2-(4-Methyl-3-cyclohexenyl)-2-propanol	8000-41-7	10	
				Stoddard solvent; Low boiling point naphtha - unspecified	8052-41-3	10	
				Palladium;E 101O/W	7440-05-3	1	
		End Terminal 2018	0.000003	Nickel	7440-02-0	80	
				Chromium	7440-47-3	20	
		Marking White 2019	0.000003	Bisphenol A epoxy resin E-03;2,2'-[(1-methylethylidene)bis(4,1-phenyleneoxymethylene)]bis-oxiranhomopolymer	25085-99-8	50	
				Barium sulfate;BaSO4	7727-43-7	15	
				Titanium dioxide	13463-67-7	30	
				Naphtha; Low boiling point naphtha	8030-30-6	5	
		Over Coating 2018	0.000030	4,4'-propane-2,2-diylidiphenol - 2-(chloromethyl)oxirane (1:1)	25068-38-6	40	
				Silicon dioxide;Silica	60676-86-0	30	
				Talc	14807-96-6	10	

				2-butoxyethoxy ethanol(DEGBE)	112-34-5	20	Diethylene glycol monobutyl
		Resistive Element 2018	0.000026	Silver;	7440-22-4	50	
				Palladium;E 101O/W	7440-05-3	15	
				Ruthenium dioxide	12036-10-1	30	
				Frits,chemicals;Bleihaltige Fritten, Chemikalien	65997-18-4	5	
ESD-P	0.0047	End Termination 1	0.000142	Silver;	7440-22-4	60	
				2-butoxyethoxy ethanol(DEGBE)	112-34-5	10	
				Methoxypropoxypropanol	34590-94-8	10	
				3-Glycidoxypopyltrimethoxysilane;[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	10	
				Others	-	10	Polyether Resins
		External electrode Ni 1	0.00002	Nickel	7440-02-0	100	
		External electrode Sn 1	0.00003	Tin	7440-31-5	100	
		First Termination 1	0.00011	Silver;	7440-22-4	70	
				Fiber Glass Wool	65997-17-3	5	
				Ethyl cellulose	9004-57-3	5	
				Terpineol;2-(4-Methyl-3-cyclohexenyl)-2-propanol	8000-41-7	5	
				2-Butoxyethanol	111-76-2	5	
				Benzyl alcohol;alpha-Hydroxytoluene	100-51-6	5	
				Resin acids and Rosin acids, esters with pentaerythritol;PENTAERYTHRITYL ROSINATE	8050-26-8	5	
		Internal Electrode 1	0.0001	Palladium;E 101O/W	7440-05-3	55	
				Ethyl cellulose	9004-57-3	5	
				p-menthan-8-ol;1-methyl-4-isopropylcyclohexane-8-ol	498-81-7	30	
				Normal alkane;Normal paraffins	64771-72-8	10	
		Main body : Metal Oxide	0.0039	Zinc oxide; Zinc white; C.I. pigment white 4	1314-13-2	100	
		Others additives in Metal	0.00044	Neodymium oxide;Dineodymium trioxide	1313-97-9	1.89	
				Cobalt oxide (Co3O4)	1308-06-1	2.77	
				Zinc oxide; Zinc white; C.I. pigment white 4	1314-13-2	91.82	
				Praseodymium oxide;Praseodymium(III,IV) oxide	12037-29-5	3.52	
		Overcoat 1	0.00001	Others	-	60	Epoxy resin/182697-62-7
				Solvent naphtha	64742-94-5	15	
				Carbon Black	1333-86-4	15	
				Talc	14807-96-6	10	
MLCC	0.0016	Ceramic element	0.001	Barium oxide, obtained by calcining witherite	1304-28-5	60	
				Titanium dioxide	13463-67-7	30	

				Others	-	10	Misc
		Inner electrode-MLCC	0.00028	Nickel	7440-02-0	100	
		Nickel Plating Layer	0.00002	Nickel	7440-02-0	100	
		Tin Plating Layer	0.00005	Tin	7440-31-5	100	
		Outer electrode	0.00019	Copper (metallic)	7440-50-8	90	
				diboron trioxide; boric oxide	1303-86-2	2	
				Silicon dioxide	7631-86-9	8	
IND	1.4228	CORE	1.25	Iron;	7439-89-6	97	
				Carbon;Activated carbon	7440-44-0	1	
				Nitrogen;Diatomicnitrogen	7727-37-9	1	
				Oxygen;Dioxygen	7782-44-7	1	
		INK	0.000071	2-Butanone;Ethyl methyl ketone	78-93-3	90	
				Others	-	10	Chrome III -Complex Dye
		Terminal	0.056	Copper (metallic)	7440-50-8	99.8	
				Nickel	7440-02-0	0.02	
				Tin	7440-31-5	0.18	
		WIRE-COPPER	0.112	Copper (metallic)	7440-50-8	100	
		WIRE-COATING	0.0071	Polyurethane; TPU	9009-54-5	100	
Conn	0.1322	Housing	0.05	Fiber Glass Wool	65997-17-3	29	
				OP 935;Aluminum diethylphosphinate	225789-38-8	9	
				Polyamide;Polyamide resin	63428-84-2	61.9	
				Carbon Black	1333-86-4	0.1	
		Fitting Nail.	0.041	Copper (metallic)	7440-50-8	65	
				Zinc	7440-66-6	34.96	
				Lead;	7439-92-1	0.02	
				Iron;	7439-89-6	0.02	
		Plating Au	0.0001	Gold	7440-57-5	99.97	
				Cobalt	7440-48-4	0.03	雜質
		Plating Ni.	0.00010	Nickel	7440-02-0	100	
		Terminal	0.041	Copper (metallic)	7440-50-8	93.8	
				Tin	7440-31-5	6	
				Phosphorus	7723-14-0	0.2	
Fuse-C	0.0030	Ag Conductive Paste	0.000070	Silver;	7440-22-4	100	
		Ag Termination Paste	0.0007	Silver;	7440-22-4	95	
				Bismuth	7440-69-9	5	
		Alumina Substrate	0.00183	Aluminum oxide;	1344-28-1	100	Alumina
		Blue Dielectric Glass Paste	0.00014	Fiber Glass Wool	65997-17-3	100	Fibrous glass
		Green Overglaze Paste	0.000027	Fiber Glass Wool	65997-17-3	100	Fibrous glass

		Nickel Anode	0.0001	Nickel	7440-02-0	100	
		Tin Anode	0.0001	Tin	7440-31-5	100	
Solder	0.285	solder	0.285	Tin	7440-31-5	85	
				Silver;	7440-22-4	2.7	
				Copper (metallic)	7440-50-8	0.4	
				Resin acids and resin acids, esters with glycerol;Resin acids and Rosin acids, esters with glycerol	8050-31-5	11.9	Vehicle ; modified resin, glycol ether, activaor, additive
ACF-OLB	4.704	Anisotropic Conductive Film	4.704	Nickel	7440-02-0	2	
				Others	-	66	Epoxy Compound
				Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	25	
				Others	-	7	CAS No.27610-48-6 (1,6-
LB	0.3853	FPC-Coverlay(GP)	0.0885	Others	-	50	Adhesive of epoxy resin
				Poly(pyromellitic dianhydride-co-4,4'-oxydianiline)	25038-81-7	50	
		FPC-PI (Stiffener)	0.0175	Poly(pyromellitic dianhydride-co-4,4'-oxydianiline)	25038-81-7	86	
				Others	-	9	Interlayer adhesive
				Silicon dioxide	7631-86-9	5	
		FPC-Thermosetting ink	0.0125	Others	-	55	Modified polyester resin
				Solvent naphtha	64742-94-5	5	
				Titanium dioxide	13463-67-7	25	
				Barium sulfate;BaSO4	7727-43-7	15	
		FPC-White marking ink	0.0125	Titanium dioxide	13463-67-7	29	
				Others	-	30	Bisphenol A-(epichlorohydrin)
				Talc	14807-96-6	18	
				2-Butoxyethanol	111-76-2	9.5	
				Silicon dioxide	7631-86-9	3	
				Solvent naphtha	64742-94-5	5	
				Others	-	5	Amine compound
				Naphthalene	91-20-3	0.5	在高溫製程中會揮發
		FPC-Pure glue	0.0113	Polyacrylic acid	9003-01-4	80	
				Others	-	4	Curing agent
				Others	-	1	Inorganic Additive
				Silicon dioxide	7631-86-9	15	
		FPC-Potassium gold cyanide	0.0184	Potassium dicyanoaurate;Aurate(1-),bis(cyano-C)-, potassium	13967-50-5	100	
		FPC-Nickel cake	0.0184	Nickel	7440-02-0	100	

		FPC-Double sided adhesive	0.10	Copper (metallic)	7440-50-8	90	
				Poly(pyromellitic dianhydride-co-4,4'-oxydianiline)	25038-81-7	10	
		LED-Chip	0.0010	Indium Tin Oxide	50926-11-9	0.052	
				Gallium; Liquid gallium; Ga	7440-55-3	4.646	
				Indium;INE 07PB	7440-74-6	2.463	
				Nitrogen;Diatomicnitrogen	7727-37-9	1.796	
				Aluminum oxide;	1344-28-1	88.717	
				Chromium	7440-47-3	0.001	
				Gold	7440-57-5	0.502	
				Titanium	7440-32-6	0.019	
				Platinum	7440-06-4	0.044	
				Aluminium;	7429-90-5	0.011	
				Silica, Crystalline	14808-60-7	0.837	
				Titanium dioxide	13463-67-7	0.912	
		LED-Gold wire	0.0005	Gold	7440-57-5	99.99	
				Others	-	0.01	雜質
		LED-Housing	0.0023	Others	-	64	Polyester
				Titanium dioxide	13463-67-7	18	
				Fiber Glass Wool	65997-17-3	18	
		LED-Lead frame	0.0019	Copper (metallic)	7440-50-8	97.52	
				Iron;	7439-89-6	2.3	
				Zinc	7440-66-6	0.09	
				Phosphorus	7723-14-0	0.08	
				Lead;	7439-92-1	0.01	
		LED-Phosphor	0.0007	Others	-	100	Aluminum Cerium Yttrium
		LED-Plating	0.0011	Silver;	7440-22-4	100	
		LED-Silicone-A	0.00126	Others	-	75	Polysiloxane
				Others	-	2	Cyclosiloxane
				2,4,6,8-Tetravinyl-2,4,6,8-tetramethylcyclotetrasiloxane;	2554-06-5	23	
		LED-Silicone-B	0.0013	Others	-	22	Trisiloxane
				Others	-	74	Silsesquioxane
				Others	-	2	Silicone resin
				Others	-	2	Polysiloxane
		Solder	0.1	Tin	7440-31-5	86	
				Bismuth	7440-69-9	2	
				Copper (metallic)	7440-50-8	2	

				Silver;	7440-22-4	0.3	
				Others	-	5.5	松香
				Others	-	4.2	溶劑
PC	1.0	Plastic pellets (PC-122B)	1.0	POLY(BISPHENOL A CARBONATE);2,2-bis(4-Hydroxyphenyl)propanepolycarbonate	24936-68-3	99	
				Others	-	1	Additives
Bezel	24.01	Mylar	0.1	Poly(ethylene terephthalate);PET	25038-59-9	20	
				Butyl acrylate-methyl methacrylate polymers;Butyl acrylate-methyl methacrylate copolymer	25852-37-3	70	
				PIPERYLENE/BUTENE/PENTENE	152698-66-3	10	
		Rubber	0.10	VINYL TERMINATED	68083-19-2	98	
				Silicone;Poly(dimethylsiloxane);Silicon	63148-62-9	1	
				2,5-Dimethyl-2,5-di(tert-butylperoxy)hexane;Di-tert-butyl 1,1,4,4-tetramethyltetramethylene diperoxide	78-63-7	1	
		Raw materials - Iron	23.8	Iron;	7439-89-6	98.08	
				Carbon;Activated carbon	7440-44-0	0.3	
				Manganese and its compounds	7439-96-5	0.67	
				Sulfur	7704-34-9	0.04	
				Zinc	7440-66-6	0.77	
				Aluminium;	7429-90-5	0.08	
				Ferrophosphorus;Iron alloy, base, Fe,P	8049-19-2	0.05	
				Silicon;	7440-21-3	0.01	
		Ink	0.010	2-Butanone;Ethyl methyl ketone	78-93-3	80	
				Ethanol	64-17-5	10	
				4-(2-METHYL-ALLYL)-BENZOIC ACID;4-(2-METHYL-2-PROPENYL)BENZOIC ACID	168194-08-9	10	
Rear	89.00	MYLAR-HX-006T	0.10	2-Ethylhexyl acrylate	103-11-7	72	壓克力感壓膠
				POLYSTER RESIN	113669-95-7	28	聚酯膜
		MYLAR-HX-010T	0.10	2-Ethylhexyl acrylate	103-11-7	22	壓克力感壓膠
				POLYSTER RESIN	113669-95-7	78	聚酯膜
		Mylar	0.10	Others	-	7.9	color pigment(商业机密)
				Others	-	44	Acrylic resin
				Poly(ethylene terephthalate);PET	25038-59-9	48.058	
				Dibutyltin dilaurate; Stannane,dibutylbis[(1-oxododecyl)oxy]-	77-58-7	0.018	

				Antimony trioxide; Diantimony trioxide; Antimony(III) oxide;	1309-64-4	0.024	
		Mylar	0.10	Polyacrylic acid; 2-Propenoic acid homopolymer	9003-01-4	22.75	
				polypropylene; PP	9003-07-0	77.25	
		Mylar	0.10	Poly(ethylene terephthalate);PET	25038-59-9	35	
				2-Ethylhexyl acrylate	103-11-7	65	
		Rubber	0.10	VINYL TERMINATED	68083-19-2	98	
				Silicone;Poly(dimethylsiloxane);Silicon	63148-62-9	1	
				2,5-Dimethyl-2,5-di(tert-butylperoxy)hexane;Di-tert-butyl 1,1,4,4-tetramethyltetramethylene diperoxide	78-63-7	1	
		Rubber	0.10	Silicon dioxide	7631-86-9	96	
				Others	-	4	商業機密
		Raw materials	88.18	Silicon;	7440-21-3	0.25	
				Iron;	7439-89-6	0.4	
				Copper (metallic)	7440-50-8	0.1	
				Manganese and its compounds	7439-96-5	0.1	
				Magnesium	7439-95-4	2.5	
				Zinc	7440-66-6	0.1	
				Aluminium;	7429-90-5	96.3	
				Chromium	7440-47-3	0.25	
		Ink	0.0100	2-Butanone;Ethyl methyl ketone	78-93-3	80	
				Ethanol	64-17-5	10	
				4-(2-METHYL-ALLYL)-BENZOIC ACID;4-(2-METHYL-2-PROPENYL)BENZOIC ACID	168194-08-9	10	
		Rivets-Steel	0.1	Carbon;Activated carbon	7440-44-0	0.09	
				Manganese and its compounds	7439-96-5	1.05	
				Sulfur	7704-34-9	0.35	
				Iron;	7439-89-6	98.42	
				Phosphorus	7723-14-0	0.09	
		Rivets-Plating Ni	0.01	Nickel	7440-02-0	100	
Protect Film	2.6700	Protect Film	2.67	polypropylene; PP	9003-07-0	100	
Db Adhesive	0.0101	TAPE	0.01	Poly(ethylene terephthalate);PET	25038-59-9	20	
				2-Propenoic acid, butyl ester, polymer with	25767-47-9	71	
				PIPERYLENE/BUTENE/PENTENE	152698-66-3	9	
Conductive Tape	0.0290	TAPE	0.0290	Others	-	40	Polyester Fabric
				Nickel	7440-02-0	3	

				Copper (metallic)	7440-50-8	16	
				Hot Melt Resin; b-D-Glucopyranoside,(2E)-3-phenyl-2-propen-1-yl;b-D-Glucopyranoside,(2E)-3-phenyl-2-propenyl (9CI)	85026-55-7	41	
Isolation_Tape	4.2000	TAPE	1.176	2-Propenoic acid,2-methyl-, methyl ester, homopolymer	9011-14-7	42	
				Poly(ethylene terephthalate);PET	25038-59-9	58	
		TAPE	2	Poly(ethylene terephthalate);PET	25038-59-9	30	
				2-Ethylhexyl acrylate	103-11-7	70	
		PET	0.672	Poly(ethylene terephthalate);PET	25038-59-9	97	
				Carbon Black	1333-86-4	3	
Sponge Tape	0.302	TAPE	0.060	Poly(ethylene terephthalate);PET	25038-59-9	30	
				2-Ethylhexyl acrylate	103-11-7	70	
		TAPE	0.241	SILICONE RUBBER;polydimethylsiloxanerubber	63394-02-5	96	
				Silicone;Poly(dimethylsiloxane);Silicon	63148-62-9	0.4	
				Silicon dioxide	7631-86-9	0.3	
				Carbon Black	1333-86-4	0.3	
				Bis(tert-butylldioxyisopropyl)benzene;Bis[1-(tert-butylperoxy)-1-methylethyl]benzene	25155-25-3	2	
				Poly(ethylene terephthalate);PET	25038-59-9	1	
Thermal Tape	0.32	Thermal Pad	0.32	Aluminum oxide;	1344-28-1	75	
				Acrylic acid	9063-87-0	20	
				Fiber Glass Wool	65997-17-3	5	
Label ID	0.4000	HTYL White PET_Adhesive	0.10	prop-2-enoic acid - 2-ethylhexyl prop-2-enoate (1:1)	25134-51-4	30	
				Resin acids and Rosin acids, polymd., esters with pentaerythritol;Pentalyn K	65997-12-8	25	
				2-Propenoic acid, polymer with butyl 2-propenoate and ethyl 2-propenoate;	27322-15-2	45	
		HTYL75#White PET Coated	0.27	Poly(ethylene terephthalate);PET	25038-59-9	80	
				silica;silicon dioxide;	14464-46-1	20	
		Black ink	0.03	Others	-	20	丙烯酸多元醇脂聚合物

				Poly[oxy(methyl-1,2-ethanediyl)],a,a',a"-1,2,3-propanetriyltris[w-[(1-oxo-2-propen-1-yl)oxy]-;Actilane 432	52408-84-1	26	
				2-Propenoic acid, 2-[[2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl;Aronix M 408	94108-97-1	10	
				1-Butanone,2-(dimethylamino)-2-[(4-methylphenyl)methyl]-1-[4-(4-morpholinyl)phenyl]-;Irgacure 379	119344-86-4	3	
				2,4-Diethyl-9H-thioxanthen-9-one	82799-44-8	3	
				4-Methylbenzophenone;Phenyl p-tolyl ketone	134-84-9	3	
				Others	-	3	二乙氨基酮类衍生物
				Carbon Black	1333-86-4	16	
				Carbonic acid,magnesium salt	546-93-0	3	
				Poly(ethylene)	9002-88-4	3	
				Polyacrylic acid; 2-Propenoic acid homopolymer	9003-01-4	10	